



HBU406

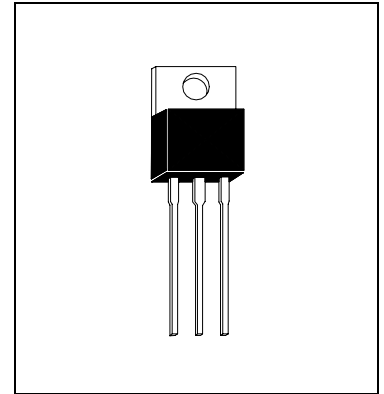
NPN EPITAXIAL PLANAR TRANSISTOR

Description

The HBU406 is designed for use in TV Horizontal output and Switching applications.

Features

- High Breakdown Voltage



Absolute Maximum Ratings

- Maximum Temperatures
 Storage Temperature -50 ~ +150 °C
 Junction Temperature 150 °C Maximum
- Maximum Power Dissipation
 Total Power Dissipation (Tc=25°C) 60 W
- Maximum Voltages and Currents (Ta=25°C)
 VCEO Collector to Emitter Voltage 200 V
 VEBO Emitter to Base Voltage 6 V
 IC Collector Current 7 A
 IB Base Current 4 A

Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
*BVCEO	200	-	-	V	IC=100mA, IB=0
ICES	-	-	5	mA	VCE=400V
IEBO	-	-	1	mA	VEB=6V, IC=0
*VCE(sat)	-	-	1	V	IC=5A, IB=0.5A
*VBE(sat)	-	-	1.2	V	IC=5A, IB=0.5A
*hFE1	25	-	-		IC=500mA, VCE=5V
*hFE2	30	-	125		IC=2A, VCE=5V
*hFE3	10	-	-		IC=5A, VCE=5V

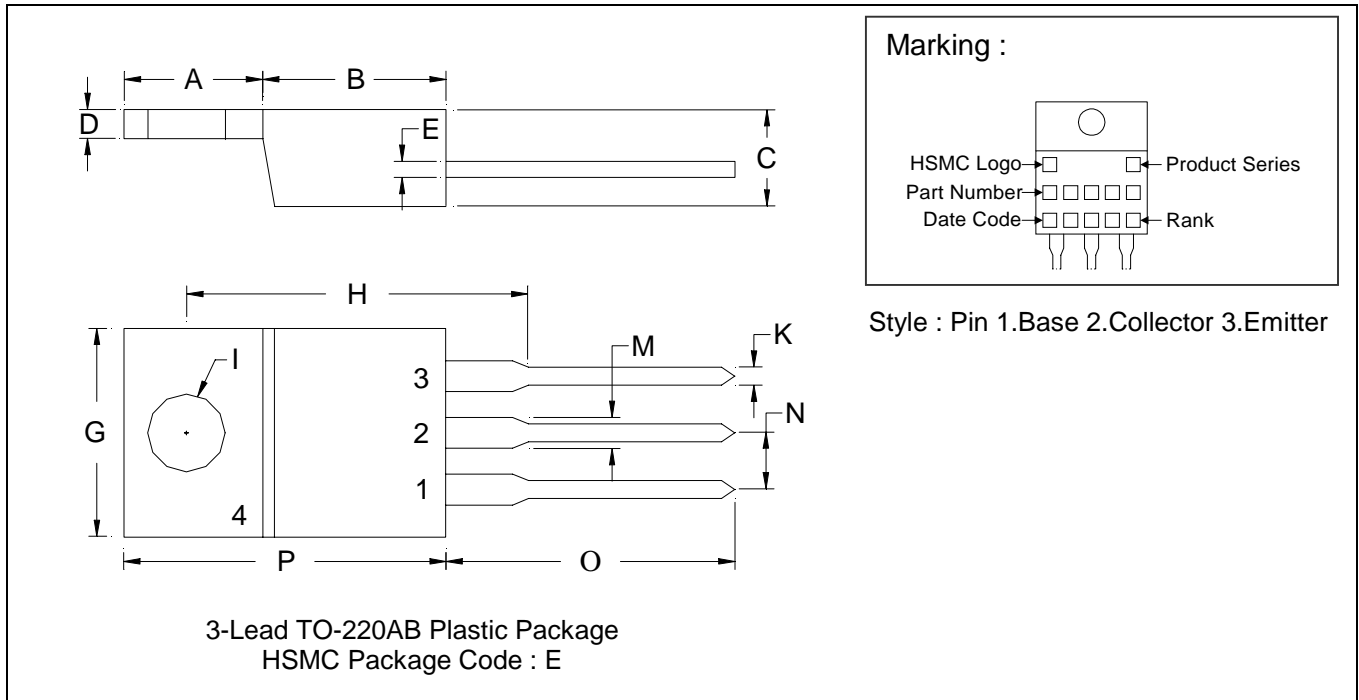
*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

Classification Of hFE2

Rank	A	B	C
Range	30-45	35-85	75-125



TO-220AB Dimension



*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.2197	0.2949	5.58	7.49	I	-	*0.1508	-	*3.83
B	0.3299	0.3504	8.38	8.90	K	0.0295	0.0374	0.75	0.95
C	0.1732	0.185	4.40	4.70	M	0.0449	0.0551	1.14	1.40
D	0.0453	0.0547	1.15	1.39	N	-	*0.1000	-	*2.54
E	0.0138	0.0236	0.35	0.60	O	0.5000	0.5618	12.70	14.27
G	0.3803	0.4047	9.66	10.28	P	0.5701	0.6248	14.48	15.87
H	-	*0.6398	-	*16.25					

Notes : 1.Dimension and tolerance based on our Spec. dated Sep. 07,1997.
 2.Controlling dimension : millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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